

QF3115A

No Clean Liquid Flux



Product Description

QF3115A is RMA flux suitable for both conventional SnPb and Pb free applications. This flux has been formulated such that no solder balls are formed and bridging problems are minimized.

Application

QF3115A is specially formulated for foaming as well as spraying process. Recommended onboard preheat temperature is 80 – 110°C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 year under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, QF3115A can be stored for up to 6 months. QF3115A is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Light yellow
Specific Gravity @ 25°C	0.823 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	15.0 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	0.08 +/- 0.01 wt%
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	49.0 +/- 5% mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
<small>JIS Z 3197 8.5.3</small>	
Electromigration (85°C, 88.5%RH, 596hrs)	> 1 x 10 ¹¹ Ω, Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROM1
<small>IPC J-STD-004</small>	
Spread Factor	>80% (SnCu0.7 & SCS7)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	>90% (SnPb)
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Matte

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